

ABSTRACT

A stacked microelectronic assembly comprises a continuous sheet including a core panel and a plurality of side panels, each having a folded portion that connects the side panel to an edge of the core panel. At least two of the panels are at least partially horizontally aligned with one another in a stack. During manufacture of a stacked microelectronic assembly, failed microelectronic elements are identified and associated side panels thereof are simply cut-off. This results in the production of a usable stacked microelectronic assembly albeit of reduced capacity, or reduced functionality.

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